

Title (en)  
SUBSTRATE CARRIER

Title (de)  
SUBSTRATHALTER

Title (fr)  
SUPPORT DE SUBSTRAT

Publication  
**EP 1145292 A1 20011017 (DE)**

Application  
**EP 99963537 A 19991215**

Priority  
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Abstract (en)  
[origin: DE19859467A1] The invention relates to a substrate carrier for holding substrates, especially semiconductor wafers. Good sealing of the wafer surface and electrical contact are made possible in that the substrate carrier has a first and a second part having a central opening matching the form of the substrate, wherein the substrate is received between the first and the second part and a peripheral seal having at least one undercut is provided in the inner periphery of the second part.

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**H01L 21/00**

IPC 8 full level  
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